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MULLARD SPACE SCIENCE LABORATORY UNIVERSITY COLLEGE LONDON Author: C Brockley-Blatt

SPIRE – STRUCTURE DECLARED PROCESSESS LIST

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Change Record

IS	SSUE	DATE	
0.1	Septem	ber 2001 Ne	w document
2	22 Nov	ember 2002 Issu	ued
3	January	2003 Up	dated with Silver Soldering
4	March	2003 Up	dated to remove processes not used
5	June 20	04 Un	dated to include new processes 6 – 10

Table of Contents

- 1. Scope of Document
- 2. Applicable and Reference Documents
- 3. Declared Processes List

Glossary

All terms are listed in the CIDL.

1 Scope of Document

This document presents all the processes to be used all along the design, development and manufacture of the structure for SPIRE.

2. Applicable and Reference Documents

All documents are listed in Figure 3.2 of the CIDL.

3 Declared Processes List

The Structure Declared Processes List, which consists of multiple arrays of 10 columns which shall be completed as indicated in AD04, is presented here below:

Processes should be grouped in the table below:

Group Type	Used
1. Adhesive Bonding	✓
2. Composite Manufacturing	✓
3. Encapsulation/Molding	N/A
4. Painting/Coating	✓
5. Cleaning	✓
6. Welding/Brazing	✓
7. Crimping/Stripping/Wire Wrapping	✓
8. Soldering	N/A
9. Surface Treatment	N/A
10. Plating (Allo-chroming)	✓
11. Machining	✓
12. Forming	✓
13. Heat Treatment	✓
14. Special Fabrication	N/A
15. Marking	✓
16. Miscellaneous Processes	N/A
17. Inspection Procedure	✓

DECLARED PROCESSES LIST

PROJECT: HERSCHEL **SPIRE**

Issue No 5

EXPERIMENT: EXPERIMENTERS: MULLARD SPACE SCIENCE LABORATORY (MSSL)

C Brockley-Blatt PREPARED BY:

Itm No	Process	Specification	Description/ identification	Use and location	User code	Associated DML items	Criticality of process	Approval Status	Project Sign Off	ESA Sign Off	ESA Comments
1.	Stycast 2850 FT Black	Commercial 2 part epoxy adhesive for cryogenics		Internal and external wiring harness supports	MSSL	10-02	Non-critical				
2.	Crimp connections	ECSS-Q-70-26	Fabrication of wiring harnesses	Internal and external wiring harnesses	MSSL	19-01	Non-critical				
3.	Alocrom 1200	MOD 03-18	Chromating - Commercial process	Various	MSSL	01-01,02, 01-03	Non-critical				
4.	Heat Treatment T 73	Mil-H-6088-F	Thermal treatment	Treatment for aluminium	SNL	01-01	Non-critical				
5	Silver Soldering	MSSL In-House Procedure	Brazing using a 55% silver solder (rest is zinc, copper and Tin)	Thermal joints on the thermal bus bar	MSSL	07-01	Non-critical				

DECLARED PROCESSES LIST

PROJECT: HERSCHEL **SPIRE**

Issue No 5

EXPERIMENT: EXPERIMENTERS: MULLARD SPACE SCIENCE LABORATORY (MSSL)

C Brockley-Blatt PREPARED BY:

Itm No	Process	Specification	Description/ identification	Use and location	User code	Associated DML items	Criticality of process	Approval Status	Project Sign Off	ESA Sign Off	ESA Comments
6.	Goldplating	British Telecom spec. M468A and MIL spec G45204B type 1C		Thermal Straps and 300mK busbar	Walton Plating, Woking	10-02	Non-critical				
7.	Composite Manufacture	In-house Procedure	Fabrication of FPU and detector box mounts	FPU and detector box mounts	B3 Technologies Shalford	15-01, 15-02	Non-critical				
8.	Compression welding	In-House Procedure	Welding under pressure and heat (nominally 900 deg C)	Level 0 Thermal Straps	EMS, Germany	02-01, 02-02	Non-Critical				
9.	Electron Beam Welding	In House Procedure	Stake welds at 1mm wide by 13.5mm	Level 0 Thermal straps	EBP, Woking	02-01, 02-02	Non-critical				
10.	Glue Joint Isolation	In house-procedure - MSSL-MEG-PRC- 2003-01.	Electrical isolation	Thermal Straps	MSSL	02-01, 02-02 10-01	Non-critical				